100% Material Declaration Data Sheet VQG100

Average Weight: 0.5 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.01995**	**3.99%**
	Silicon	7440-21-3	100.00		0.01995	
Die Attach Material					**0.00315**	**0.63%**
	Silver	7440-22-4	78.00		0.002457	
	Epoxy (EP)	Trade Secret	22.00		0.000693	
Mold Compound					**0.32425**	**64.85%**
	Epoxy Resin (EP)	Trade Secret	9.00		0.0291825	
	Phenolic Resin	Trade Secret	7.00		0.0226975	
	Carbon Black	1333-86-4	0.50		0.00162125	
	Silica	60676-86-0	82.50		0.26750625	
	Bismuth	7440-69-9	Max 1.00		0.0032425	
Leadframe					**0.139**	**27.80%**
	Copper	7440-50-8	96.57		0.1342323	
	Nickel	7440-02-0	2.70		0.003753	
	Silicon	7440-21-3	0.58		0.0008062	
	Magnesium	7439-95-4	0.15		0.0002085	
Leadframe Plating					**0.00225**	**0.45%**
	Silver	7440-22-4	100.00		0.00225	
Bond Wire					**0.00355**	**0.71%**
	Gold	7440-57-5	100.00		0.00355	
Ext. Plating					**0.00785**	**1.57%**
	Tin	7440-31-5	100.00		0.00785	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/20/06	1.0	Initial release.
7/10/06	1.1	100% Material Declaration.
9/29/06	1.2	Updated component descriptions.

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